

REPLACEMENT CLAIMS

Please substitute the following claims for the pending claims with the same number.

1. (Amended) A semiconductor device comprising:

a semiconductor chip;

an external connection electrode connected to the chip; and

a resin package which covers the chip and has a mounting surface;

wherein the electrode includes a thick portion and a thin portion, the thick portion being exposed to outside only at the mounting surface of the package.

3. (Amended) The semiconductor device according to claim 2, wherein the projection includes a bottom surface exposed to outside at the mounting surface of the package and four side surfaces entirely covered with the package.

5. (Amended) The semiconductor device according to claim 1, wherein the electrode includes two thick portions spaced from each other and a thin portion connecting the thick portions, both of the two thick portions being exposed to outside only at the mounting surface of the package.

8. (Amended) The semiconductor device according to claim 1, further including an additional electrode separate from the external connection electrode, the additional electrode

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including a thick portion and a thin portion, the thick portion of the additional electrode being exposed to outside only at the mounting surface of the package.

10. (Deleted)